



8755 W. Higgins Road
Suite 500
Chicago, Illinois USA 60631

July 7, 2026

PCN # ESW490-69 – Alternate Backend Location Approval of SIDAC DO-15 Package Products

To our valued customers,

Littelfuse would like to notify you of a newly approved backend location for SIDAC DO-15 products as part of our Business Continue Plan. In addition, this change supports our ongoing product quality and sustainability improvement initiatives through the adoption of halogen-free molding compound materials. The factory is fully approved for all assembly, test, and packing operations.

All affected products have been fully qualified in accordance with established performance and reliability criteria. Please see the attached pages for change details, qualification results and affected part numbers. Full qualification data and/or samples will be available upon request.

Form, fit, function changes: N/A

Part number changes: None

Effective date: October 5, 2026

Replacement products: N/A

Last time buy: N/A

This notification is for your information and acknowledgement. If you require specific data or product samples to certify this change, please contact Littelfuse within 90 days of the notification date.

If you have any other questions or concerns, please contact me or your local sales team.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Maggie Xu
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800 E. Northwest Highway Des Plaines, IL 60016

Product/Process Change Notice (PCN)

PCN#: ESW490-69 **Date:** July 7, 2026

Product Identification:

SIDAC DO-15 Package Products

Implementation Date for Change:

October 5, 2026

Contact Information

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Category of Change:

- ☐ Assembly Process
- ☐ Data Sheet
- ☐ Technology
- ☐ Discontinuance/Obsolescence
- ☐ Equipment
- ☒ Manufacturing Site
- ☒ Raw Material
- ☐ Testing
- ☐ Fabrication Process
- ☐ Other: _____

Description of Change:

Approve an alternate backend assembly, test and packing location for SIDAC DO-15 Package Products with BCP consideration.

There are no changes in fit, form, function of the finished products. The affected products have been fully qualified in accordance with established performance and reliability.

Important Dates:

- ☒ Qualification Samples Available: 7/7/2026 ☐ Last Time Buy:
- ☒ Final Qualification Data Available: 7/7/2026
- ☐ Date of Final Product Shipment:

Method of Distinguishing Changed Product

- ☐ Product Mark,
- ☒ Date Code, Traceability data available upon request
- ☐ Other,

Demonstrated or Anticipated Impact on Form, Fit, Function or Reliability:

N/A

LF Qualification Plan/Results:

All affected products have been fully qualified in accordance with established performance and reliability criteria.

Customer Acknowledgement of Receipt: Littelfuse requests you acknowledge receipt of this PCN. In your acknowledgement, you can grant approval or request additional information. Littelfuse will assume the change is acceptable if no acknowledgement is received within 30 days of this notice. Lack of any additional response within 90 days of PCN issuance further constitutes acceptance of the change.

PCN Report

Prepared By : Eleana Yang, Product Engineer
 Maggie XU, Technical Support Manager
Date : July 7, 2026
Products : DO-15 SIDAC
Revision : A

1.0 Objective:

This PCN is to qualify an alternate backend manufacturing site for SIDAC DO-15 package products' assembly, test, and packing operations. There is no change in the die / wafer.

2.0 Applicable Products:

SIDAC DO-15 Package Products.
 Please see the attachments for a full list of affected part numbers.

3.0 Assembly, Process & Material Changes:

3.1 Assembly change

No change of assembly process

3.2 Process Change

No change of process method

3.3 Material Change

Material	Current OSAT	New OSAT	Change or not
Chip	Per device	Per device	No
Lead wire	$\Phi 0.78 \pm 0.005$	$\Phi 0.72 \pm 0.005$	Yes
Solder	Pb90Sn10	Pb90Sn10	No
Slug (for PNs that have)	2.78 * 1.25 * 1 / 1.2 * 0.18 Copper	2.78 * 1.25 * 1 / 1.2 * 0.18 Copper	No
Compound	EME-E1100RG (non-HF)	EME-E110G (HF)	Yes

4.0 Physical Differences/Changes:

There is no form, fit, function changes related to this PCN.
 All dimensions are the same without any change of datasheet specification.

There are slight differences in product appearance, label dimensions, reel packaging appearance,
 and the inner box dimension for the ammo pack configuration.

Item	Current OSAT	New OSAT
Product appearance		
Label dimension	115mm x 50mm	102mm x 76mm
Bulk pack packing box dimension and appearance	305mm x 77mm x 41mm	301mm x 78mm x 40mm

		
Reel pack reel dimension and appearance	Φ330mm 	Φ330mm 
Ammo pack box dimension and appearance	250mm*115mm*80mm 	259mm × 100mm x 80mm 

5.0 Qualification Test Result

All samples passed parametric and reliability test standard by Littelfuse.

Test Item	Sample P/N	Sample QTY	Littelfuse test Ref#	Contents/ Conditions	Result Summary
HTRB	K0820GURP	77 x 1	TR24-11-012633 TR24-11-012635 TR25-05-016043	At T _J max, Reverse biased at 100%V _{DRM} , 1008 hours	PASS
	K2500GHRP	77 x 1			
	K2402GRP	77 x 1			
	K3601GL	77 x 1			
H3TRB ¹	K0820GURP	77 x 1		T _A =85°C, RH=85%, Reverse biased at 80% min V _{BO} , 1008 hours	PASS
	K2500GHRP	77 x 1			
	K2402GRP	77 x 1			
	K3601GL	77 x 1			
Temperature Cycling	K0820GURP	77 x 1		-55°C & 150°C (air to air), Dwell time 15mins, 1000 cycles	PASS
	K2500GHRP	77 x 1			
	K2402GRP	77 x 1			
	K3601GL	77 x 1			
UHASt	K0820GURP	77 x 1		T _A =130°C, RH=85%, 96 hours	PASS
	K2500GHRP	77 x 1			
	K2402GRP	77 x 1			
	K3601GL	77 x 1			
ESD	K0820GURP	30 x 1		HBM 8KV	PASS
	K2500GHRP	30 x 1			
	K2402GRP	30 x 1			
	K3601GL	30 x 1			



RSH	K0820GURP	30 x 1		JESD22-B-106 270°C, 7 secs	PASS
	K2500GHRP	30 x 1			
	K2402GRP	30 x 1			
	K3601GL	30 x 1			
Solderability	K0820GURP	10 x 1		245°C, 10 secs	PASS
	K2500GHRP	10 x 1			
	K2402GRP	10 x 1			
	K3601GL	10 x 1			

Note: H3TRB condition according to detailed definition on datasheet per device

6.0 Recommendations & Conclusions:

Based on the above qualification test results, Littelfuse concluded new alternate backend location can pass the release criterion and ready to start mass production for affected products.

Appendix A: Affected Part Number List

K0820GURP	K2000GURP	K2500G	K280K1200GRP
K0900G	K2002G	K2500GAP	K281K2500GRP
K0900GRP	K2002GRP	K2500GH	K283K2401G
K0900GURP	K203K2400G	K2500GHAP	K283K2401GRP
K1050G	K203K2400GRP	K2500GHRP	K284K2401GRP
K1050GRP	K217K1300G	K2500GHU	K286K2401GRP
K1050GURP	K2200G	K2500GHURP	K287K2401GRP
K1100G	K2200GAP	K2500GRP	K288K2402GRP
K1100GRP	K2200GH	K2500GURP	K289K2502GRP
K1100GURP	K2200GHRP	K2501G	K290K2002GRP
K1120G	K2200GHU	K2501GL	K291K3002G
K1120GAP	K2200GHURP	K2501GLAP	K291K3002GRP
K1120GRP	K2200GRP	K2501GLRP	K292K2402G
K1200G	K2200GURP	K2501GRP	K292K2402GRP
K1200GRP	K2201G	K2502G	K293K1300GRP
K1200GURP	K2201GL	K2502GRP	K294K2500GRP
K1300G	K2201GLRP	K250AK1200G	K295K2200GHURP
K1300GRP	K2201GRP	K250BK1100G	K296K2201G
K1300GURP	K2202G	K250CK1200G	K296K2201GRP
K1400G	K2202GRP	K250DK2200G	K297K3601G
K1400GAP	K220K2000G	K250EK1500G	K299K1300GRP
K1400GRP	K2300G	K250FK1500G	K3002G
K1400GURP	K2300GAP	K254K2400GRP	K3002GRP
K1500G	K2300GRP	K255K2000G	K302K2401GRP
K1500GAP	K2300GURP	K255K2000GRP	K323K2401GLRP
K1500GRP	K2400G	K257K1300G	K325K2000GRP
K1500GURP	K2400GAP	K258K2400G	K327K2201GLRP
K153K2200G	K2400GH	K258K2400GRP	K328K2401GLRP



K1800G	K2400GHAP	K267K1500G	K331K2201GLRP
K1800GAP	K2400GHRP	K267K1500GRP	K332AK2201GLRP
K1800GRP	K2400GHU	K271K1050G	K332K2201GLRP
K1800GURP	K2400GHURP	K271K1050GRP	K337K1800GURP
K2000G	K2400GRP	K272K2200G	K346K2200GHRP
K2000GAP	K2400GURP	K272K2200GRP	K347K2200GRP
K2000GH	K2401G	K273K2500G	K3601G
K2000GHAP	K2401GL	K273K2500GRP	K3601GL
K2000GHRP	K2401GLRP	K274K2400G	K3601GLRP
K2000GHU	K2401GRP	K274K2400GRP	K3601GRP
K2000GHURP	K2402G	K277K2200GRP	K362K1050GURP
K2000GRP	K2402GRP	K279K1300GRP	K363K1050GURP
			K364K1500GURP